PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KESVAKUMAR V.C. MUNIANDY	03/22/2013
NAVAS KHAN ORATTI KALANDAR	03/22/2013

RECEIVING PARTY DATA

Name:	Freescale Semiconductor, Inc.	
Street Address:	6501 William Cannon Drive West	
Internal Address:	Law Department	
City:	Austin	
State/Country:	TEXAS	
Postal Code:	78735	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14292938

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

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DEE MATOCHA **Correspondent Name:**

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Address Line 2: TX30/OE62

Address Line 4: AUSTIN, TEXAS 78735

ATTORNEY DOCKET NUMBER:	MT12047AK-D01	
NAME OF SUBMITTER:	CASSIE YE	
SIGNATURE: /Cassie Ye/		
DATE SIGNED:	06/02/2014	

Total Attachments: 3

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PATENT REEL: 033012 FRAME: 0265 502834281

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

KESVAKUMAR V.C. MUNIANDY AND NAVAS KHAN ORATTI KALANDAR, BOTH OF

MALAYSIA have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE

SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, State
of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title
and interest for the United States of America in and to certain inventions relating to improvements in

STIFFENED SEMICONDUCTOR DIE PACKAGE (Docket No. MT12047AK), described, illustrated and
claimed in an application for Letters Patent of the United States of America executed by us on the dates
indicated by our signatures below, together with the entire right, title and interest in and to the application, and
in and to Letters Patent which may be issued upon the application, and upon any division, extension,
continuation or reissue thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefore in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

-1-«DOCKET NO»

> PATENT REEL: 033012 FRAME: 0266

VECVARIMAD V.C. MINIANDV	

DATE: 03-22-2013

First Witness

SIGNATURE OF WITNESS

DATE: 03-22-2013

(Month-Day-Year)

PRINTED NAME OF WITNESS

Second Witness

SIGNATURE OF WITNESS

DATE: 03-22-2013

(Month-Day-Year)

Lau Teck Beng

PRINTED NAME OF WITNESS

-2-«DOCKET_NO»

Nord,
NAVAS KHAN ORATTI KALANDAR

DATE: 03 - 22 - 20/3

First	Witness

SIGNATURE OF WITNESS

DATE: 03-22-2013 (Month-Day-Year)

Found Chee Seng PRINTED NAME OF WITNESS

Second Witness

SIGNATURE OF WITNESS

Lau Teck Beng

RECORDED: 06/02/2014

PRINTED NAME OF WITNESS

«DOCKET_NO»

PATENT REEL: 033012 FRAME: 0268